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FORM PTO-1595

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RE



SHEET

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OMB No. 0651-0011 (exp. 4/94)

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To the Assistant Commissioner for Patents:
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Takashi SUGINO
Hideo SENOO

11/27/00

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: LINTEC CORPORATION

Internal Address: _____

Street Address: 23-23, Honcho, Itabashi-ku,Tokyo 173-0001, Japan

State: _____ ZIP: _____

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: November 9, 2000

4. Application number(s) or patent number(s):

If this document is being filed together with a new application,
the execution date of the application is: November 9, 2000

A. Patent Application No.(s)

09/723083

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Kent E. BaldaufInternal Address: Webb Ziesenheim LogsdonOrkin & Hanson, P.C.Street Address: 700 Koppers Building436 Seventh AvenueCity: Pittsburgh State: PA ZIP: 15219-1818

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41).....\$ 40

- ☒ Enclosed with filing fee
☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach triplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Kent E. Baldauf

Name of Person Signing

Signature

November 27, 2000

Date

Reg. No. 25,826

Total number of pages including cover sheet, attachments and document

3

Mail documents to be recorded with required cover sheet information to:
Assistant Commissioner for Patents, U.S. Patent and Trademark Office
Office of Public Records, Crystal Gateway 4, Room 335
Washington, D.C. 20231

PATENT
REEL: 011323 FRAME: 0205

ASSIGNMENT

WHEREAS, We, Takashi SUGINO
and Hideo SENOO, residing
in 1-13-18-401 Gurinkopo Kawaguchi Saiwai-cho, Saiwai-cho, Kawaguchi-shi,***
3-33-2-405, Totsuka, Kawaguchi-shi, Saitama 338-0811, Japan, respectively,
have invented certain new and useful improvements entitled
PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE
for which we have this day executed an application for United
States Letters Patent;

AND, WHEREAS LINTEC CORPORATION, a
corporation of Japan, having a
place of business at 23-23 Honcho, Itabashi-ku, Tokyo 173-0001, Japan,
hereinafter called the "assignee", is desirous of acquiring the
entire right, title, and interest in and to said application and
the inventions and improvements therein disclosed.

NOW, THEREFORE, in consideration of One (\$1.00) Dollar
and other good and valuable consideration paid to us by said
assignee, the receipt of which is hereby acknowledged, we do
hereby assign, sell, transfer, and set over unto said assignee
the entire right, title and interest in and to said application
and the inventions and improvements therein disclosed for the
United States and all foreign countries and any Letters Patent
which may issue therefor in the United States and all foreign
countries and all divisions, reissues, continuations, renewals,
and/or extensions thereof, said assignee to have and to hold the
interests herein assigned to the full ends of the terms of said
Letters Patent and any and all divisions, reissues,
continuations, renewals, and/or extensions thereof, respectively,
as fully and entirely as the same would have been held and
enjoyed by us had this assignment not been made.

The Commissioner of Patents and Trademarks is requested
to issue such Letters Patent in accordance herewith. We covenant
that we are the lawful owners of the said application,
inventions, and improvements, that the same are unencumbered,
that no license has been granted to make, use, or vend the said
inventions or improvements or any of them, and that we have the
full right to make this assignment.

And for the consideration aforesaid, we agree jointly
and individually that we will communicate to said assignee or the
representatives thereof any facts known to us respecting said
inventions and improvements, and will, upon request, but without
expense to us, testify in any legal proceedings, sign all lawful
papers, execute all divisional, reissue, continuation, renewal,
and/or extension applications, make all rightful oaths, and
generally do all other and further lawful acts, deemed necessary
or expedient by said assignee or by counsel for said assignee, to
assist or enable said assignee to obtain and enforce full
benefits from the rights and interests herein assigned. This
assignment shall be binding upon our heirs, executors,

*** Saitama 332-0016, Japan

administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

EXECUTED November 9, 2000.

Takashi Sugino
Takashi SUGINO

Hideo Senoo
Hideo SENOO

Shin-ich Namito
Witness

Akio Nakagawa
Witness